

**=> IFW: Scan as Doc Code: SRNT <=  
Doc Date:**

## **TC 3700 Inventor Search Program**

See attached inventor searches for applications and/or patents to help resolve questions of overlapping subject matter. These searches are provided as an initial examination aid: examiners should perform updated or expanded PALM or EAST inventors searches as appropriate.

---

**Serial Number:** 10/702,085

**1.) See attached printout of inventors listed in PALM**

**2.) See attached EAST Inventor Search  
Printout shows Inventor search terms**

 **PALM INTRANET**Day : Tuesday  
Date: 4/25/2006  
Time: 11:04:04

## Inventor Information for 10/702085

<b>Inventor Name</b>	<b>City</b>	<b>State/Country</b>
SCHULZ-HARDER, JURGEN	LAUF	GERMANY

<b>Appln Info</b>	<b>Contents</b>	<b>Petition Info</b>	<b>Atty/Agent Info</b>	<b>Continuity Data</b>	<b>Foreign Data</b>	<b>Inventors</b>
-------------------	-----------------	----------------------	------------------------	------------------------	---------------------	------------------

Search Another: Application#   or Patent#

PCT /  /   or PG PUBS #

Attorney Docket #

Bar Code #

To go back use Back button on your browser toolbar.

Back to [PALM](#) | [ASSIGNMENT](#) | [OASIS](#) | [Home page](#)

US 20060022020 A1	US- PGPUB	20060202	10	Method for the production of a metal-ceramic substrate, preferably a copper ceramic substrate	228/122.1		Schulz-Harder; Jorgen
US 20050213304 A1	US- PGPUB	20050929		Cooling devices for cooling electric components, module consisting of a cooling device and electric components and assembly comprising a cooling device or module and a support	361/713	165/104.33; 257/E23.098; 257/E23.106	Exel, Karl et al.
US 20050150935 A1	US- PGPUB	20050714	11	Method for manufacturing plate stacks, particularly coolers or cooler elements made up of plate stacks	228/245		Schulz-Harder, Jorgen
US 20050126758 A1	US- PGPUB	20050616		Heat sink in the form of a heat pipe and process for manufacturing such a heat sink	165/104.21		Schulz-Harder, Jorgen
US 20050095748 A1	US- PGPUB	20050505		Method for the selective surface treatment of planar workpieces	438/107	257/700	Schulz-Harder, Jorgen
US 20040181940 A1	US- PGPUB	20040923		Conductor board and method for producing a conductor board	29/882	29/825; 29/829; 29/840	Schulz-Harder, Jorgen et al.
US 20040026482 A1	US- PGPUB	20040212		Process for the manufacture of metal-ceramic compound material in particular metal-ceramic substrates and metal-ceramic compound material especially metal-ceramic substrate manufactured according to this process	228/122.1	228/219	Schulz-Harder, Jorgen
US 20020114374	US- PGPUB	20020822		Mirror for laser applications and	372/99		Exel, Karl et al.

A1				method for manufacture of said mirror			
US 7036711 B2	USPAT	20060502		PROCESS FOR THE MANUFACTURE OF METAL-CERAMIC COMPOUND MATERIAL IN PARTICULAR METAL-CERAMIC SUBSTRATES AND METAL-CERAMIC COMPOUND MATERIAL ESPECIALLY METAL-CERAMIC SUBSTRATE MANUFACTURED ACCORDING TO THIS PROCESS	228/219	228/122.1	Schulz- Harder; Jurgen
US 7000316 B2	USPAT	20060221		Conductor board and method for producing a conductor board	29/882		Schulz- Harder; Jurgen et al.
US 6877869 B2	USPAT	20050412		Mirror for laser applications and method for manufacture of said mirror	359/845		Exel; Karl et al.
US 6638592 B1	USPAT	20031028		Ceramic/metal substrate, especially composite substrate	428/43	257/E23.07; 257/E23.106; 428/156	Schulz- Harder; Jurgen
US 6475401 B1	USPAT	20021105		Process for the manufacture of substrates with textured metalizations and holding and fastening elements for use in this process	216/20	174/250; 216/100; 216/13; 216/41	Schulz- Harder; Jurgen
US 6386278 B1	USPAT	20020514		Cooler	165/167	165/146; 165/147; 257/E23.098	Schulz- Harder; Jurgen
US 6345665 B1	USPAT	20020212		Cooling system	165/80.4	165/80.3; 257/714; 257/721; 361/690; 361/698;	Schulz- Harder; Jurgen

						361/699	
US 6345437 B1	USPAT	20020212		Process for the manufacturing of an arched metal ceramic substratum	29/825	257/E23.004; 257/E23.106; 29/829; 29/831; 29/842; 29/846; 29/848	Schulz-Harder; Jurgen et al.
US 6297469 B1	USPAT	20011002		Process for producing a metal-ceramic substrate	219/121.71	219/121.7; 427/555	Schulz-Harder; Jurgen
US 6207221 B1	USPAT	20010327		Process for producing a metal-ceramic substrate and a metal-ceramic substrate	430/312	101/129; 257/E23.106; 427/96.9; 427/97.2; 427/97.4; 427/98.4; 430/313; 430/315	Schulz-Harder; Jurgen
US 6182358 B1	USPAT	20010206		Process for producing a metal-ceramic substrate	29/846	257/E23.004; 257/E23.006; 257/E23.106; 29/847	Schulz-Harder; Jurgen
US 6093443 A	USPAT	20000725		Process for producing a ceramic-metal substrate	148/276	205/125; 205/126; 219/121.71; 228/176; 29/831; 430/314	Schulz-Harder; Jurgen et al.
US 6066219 A	USPAT	20000523		Process for producing a ceramic substrate and a ceramic substrate	156/89.11	156/307.1; 156/89.16; 156/89.18; 204/192.17; 228/198; 228/219; 257/E23.009; 427/123; 427/126.3; 427/96.8; 427/96.9	Schulz-Harder; Jurgen et al.
US 6014312 A	USPAT	20000111		Cooler or heat sink for electrical components or circuits and an electrical circuit with this heat sink	361/699	165/80.4; 257/714; 257/E23.098; 257/E23.103	Schulz-Harder; Jurgen et al.
US 5987893	USPAT	19991123		Heat exchanger	62/3.7	136/204;	Schulz-

A				arrangement and cooling system with at least one such heat exchanger arrangement		165/185; 165/80.4; 257/E23.082; 257/E23.098; 62/3.2	Harder; Jurgen et al.
US 5981036 A	USPAT	19991109		Metal ceramic substrate	428/195.1	257/E23.004; 257/E23.102; 257/E23.106; 428/209; 428/457; 428/688; 428/698; 428/702; 428/901	Schulz-Harder; Jurgen et al.
US 5924191 A	USPAT	19990720		Process for producing a ceramic-metal substrate	29/832	257/E23.106; 29/827; 29/830; 428/209	Credle, Jr.; Kenneth L. et al.
US 5721044 A	USPAT	19980224		Multiple substrate	428/210	257/E23.004; 257/E23.066; 428/209; 428/901	Schmidt; Karsten et al.
US 5676855 A	USPAT	19971014		Multiple substrate and process for its production	216/52	216/13; 216/33; 216/65; 216/76; 257/E23.004	Schulz-Harder; Jurgen
US 5527620 A	USPAT	19960618		Metal coated substrate having improved resistivity to cyclic temperature stress	428/457	257/E23.004; 257/E23.106; 428/209; 428/210; 428/212; 428/220; 428/328; 428/336; 428/357; 428/375; 428/388; 428/389; 428/403; 428/432; 428/433; 428/469; 428/901	Schulz-Harder; Jurgen
US 5508089 A	USPAT	19960416		Multiple substrate and process for its	428/209	257/E23.004; 428/210;	Schulz-Harder;

				production		428/901	Jurgen
US 5465898 A	USPAT	19951114		Process for producing a metal-ceramic substrate	228/122.1	228/903; 257/E23.067; 257/E23.105; 257/E23.106; 428/632	Schulz- Harder; Jurgen et al.
US 5382830 A	USPAT	19950117		Semiconductor module with multi-plane conductive path	257/701	257/705; 257/E25.016; 361/637; 361/807	Akyurek; Altan et al.
US 5087505 A	USPAT	19920211		Substrate, consisting of copper and ceramic layers, for printed circuit boards of electrical circuits	428/192	361/748; 428/116; 428/141; 428/152; 428/174; 428/209; 428/210; 428/426; 428/433; 428/457; 428/901	Schulz- Harder; Jurgen